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	XG7	000-XXX	Specifical	fication	IS		
Iten	Model Name	XG7000-XXX					
0verview	Dimensions	L80.0mm * W22.0mm * H2.1mm ±0.1mm					
	Interface	M. 2, PCI-e Gen4 x4 NVME Rev. 1.4					
	ew Support OS		Windows 10, Windows 11, Windows Server 2012 R2, RHEL, CentOS, Ubuntu, Linux				
Performan ce	Capacity	512GB	1TB	2TB	4TB	8TB	
	NAND Flash	3D NAND	3D NAND	3D NAND	3D NAND	3D NAN	
	Seq. Read(MB/s)	7200	7400	7400	7400	7400	
	Seq. Write(MB/s)	4400	6600	6600	6500	6600	
	TBW	300TB	600TB	1200TB	2400TB	4000T	
	Random 4k Read IOPS	720K (8TB)	720K (8TB)				
	Random 4k Write IOP	800K (8TB)					
	Random Acc. time	0. 075ms (8TB)					
Electrica 1 Reliabili ty	Input Voltage	DC 3.3V±5%	DC 3.3V±5%				
	Idle Mode(W)	0. 66W (8TB)					
	Max (W)	8. 18W (8TB)					
	Read endurance	Infinite					
	Data Retention	10year @ 25°C					
	ili MTBF	1million hours					
	ECC	4K LDPC					
	Function	Automated Bad Block Management					
Environme nt	Option Temperature	0~+70℃					
	Storage Temperature	-20~+75°C					
	Humidity	5-95%					
Warran	Limited 3-year warr	Limited 3-year warranty with free technical support					
Certif tion	L CE ROHS ECO REACH	CE, ROHS, FCC, REACH					
Statu	S MP	NO EOL					
119	®		ON				